

EELP 64, EILP 64 Core set (without clamp recess)

Series/Type: B66295G, B66295K

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ELP 64/10/50

Core (without clamp recess)

B66295

Core set EELP 64

Combination: ELP 64/10/50 with ELP 64/10/50

■ To IEC 62317-9

■ Delivery mode: single units

Magnetic characteristics (per set)

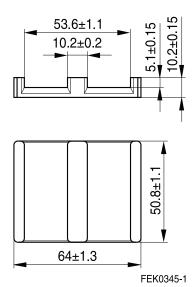
 $\Sigma I/A = 0.15 \text{ mm}^{-1}$

 $I_{e} = 79.9 \text{ mm}$

 $A_e = 519 \text{ mm}^2$

 $A_{min} = 518 \text{ mm}^2$ $V_e = 41500 \text{ mm}^3$

Approx. weight 210 g/set



ELP 64/10/50

Ungapped

Material	A _L value nH	μ _e	B _S * mT	P _V W/set	Ordering code (per piece)
N49	8000 ±30%	980	250	< 10.7 (50 mT, 500 kHz, 100 °C)	B66295G0000X149
N87	12500 ±25%	1490	300	< 26.0 (200 mT, 100 kHz, 100 °C)	B66295G0000X187
N97	12500 ±25%	1531	310	< 19.0 (200 mT, 100 kHz, 100 °C)	B66295G0000X197

^{*} H = 250 A/m; f = 10 kHz; $T = 100 ^{\circ}\text{C}$

Calculation factors (for formulas, see "E cores: general information") **EELP 64:**

Material	Relationship between air gap – A _L value		Calculation of saturation current				
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N87	820	-0.767	1280	-0.796	1182	-0.873	

Validity range: K1, K2: 0.10 mm < s < 2.00 mm

K3, K4: $480 \text{ nH} < A_1 < 4800 \text{ nH}$



ELP 64/10/50 with I 64/5/50

Core (without clamp recess)

B66295

Core set EILP 64 Combination:

ELP 64/10/50 with I 64/5/50

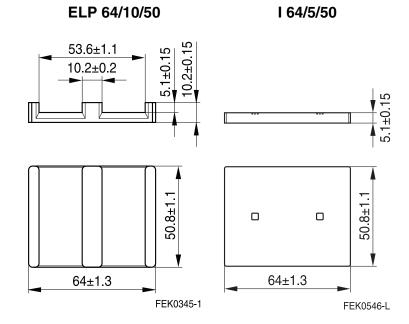
■ To IEC 62317-9

■ Delivery mode: single units

Magnetic characteristics (per set)

 Σ I/A = 0.13 mm⁻¹ I_e = 69.7 mm A_e = 519 mm² A_{min} = 518 mm² V_e = 36200 mm³

Approx. weight 185 g/set



Ungapped

Mate- rial	A _L value nH	μ_{e}	B _S * mT	P _V W/set	Ordering code (per piece)
N49	8900 ±30%	950	250	< 9.3 (50 mT, 500 kHz, 100 °C)	B66295G0000X149 (ELP core) B66295K0000X149 (I core)**
N87	14000 ±25%	1450	300	< 23.0 (200 mT, 100 kHz, 100 °C)	B66295G0000X187 (ELP core) B66295K0000X187 (I core)**

^{*} H = 250 A/m; f = 10 kHz; T = 100 °C

Calculation factors (for formulas, see "E cores: general information") EILP 64:

Material	Relationship between air gap – A _L value		Calculation of saturation current				
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N87	835	-0.790	1316	-0.796	1203	-0.873	

Validity range: K1, K2: 0.10 mm < s < 2.00 mm

K3, K4: 480 nH < A_L < 4800 nH

^{**} Plate-type tool type



Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see chapter "Definitions", section 8.1.

Effects of core combination on A_I value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see chapter "Definitions", section 8.2.

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Processing notes

- The start of the winding process should be soft. Else the flanges may be destroid.
- To strong winding forces may blast the flanges or squeeze the tube that the cores can no more be mount.
- To long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyd of the tin bath or burned insulation of the wire. For detailed information see chapter "Processing notes", section 8.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.



Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A_{e}	Effective magnetic cross section	mm ²
A_L	Inductance factor; $A_L = L/N^2$	nH
A_{L1}^{-}	Minimum inductance at defined high saturation ($= μ_a$)	nH
A _{min}	Minimum core cross section	mm ²
A _N	Winding cross section	mm ²
A_R	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega = 10^{-6} \Omega$
В	RMS value of magnetic flux density	Vs/m², mT
ΔΒ	Flux density deviation	Vs/m², mT
Ê	Peak value of magnetic flux density	Vs/m², mT
ΔÂ	Peak value of flux density deviation	Vs/m², mT
B_DC	DC magnetic flux density	Vs/m², mT
B_R	Remanent flux density	Vs/m², mT
B_S	Saturation magnetization	Vs/m², mT
C_0	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient DF = d/μ_i	
d	Disaccommodation coefficient	
E_a	Activation energy	J
f	Frequency	s−1, Hz
f _{cutoff}	Cut-off frequency	s ^{−1} , Hz
f _{max}	Upper frequency limit	s−1, Hz
f_{min}	Lower frequency limit	s ^{−1} , Hz
f _r	Resonance frequency	s ^{−1} , Hz
f_{Cu}	Copper filling factor	
g	Air gap	mm
Н	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H_{DC}	DC field strength	A/m
H_c	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 ⁻⁶ cm/A
h/μ_i^2	Relative hysteresis coefficient	10 ⁻⁶ cm/A
I	RMS value of current	Α
I_{DC}	Direct current	Α
Î	Peak value of current	Α
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
k_3	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



Symbols and terms

Symbol	Meaning	Unit
ΔL/L	Relative inductance change	Н
L ₀	Inductance of coil without core	Н
L _H	Main inductance	Н
L _p	Parallel inductance	Н
L _{rev}	Reversible inductance	Н
L _s	Series inductance	Н
l _e	Effective magnetic path length	mm
I _N	Average length of turn	mm
N	Number of turns	
P_Cu	Copper (winding) losses	W
P _{trans}	Transferrable power	W
P _V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = $\omega L/R_s$ = 1/tan δ_L)	
R	Resistance	Ω
R_{Cu}	Copper (winding) resistance (f = 0)	Ω
R _h	Hysteresis loss resistance of a core	Ω
ΔR _h	R _h change	Ω
R _i	Internal resistance	Ω
R _p	Parallel loss resistance of a core	Ω
R_s^r	Series loss resistance of a core	Ω
R _{th}	Thermal resistance	K/W
R _V	Effective loss resistance of a core	Ω
S	Total air gap	mm
Т	Temperature	°C
ΔΤ	Temperature difference	K
T _C	Curie temperature	°C
t	Time	s
t _v	Pulse duty factor	
tan δ	Loss factor	
tan δ_L	Loss factor of coil	
tan δ_r	(Residual) loss factor at $H \rightarrow 0$	
tan $\delta_{\mathbf{e}}$	Relative loss factor	
tan δ_{h}	Hysteresis loss factor	
tan δ/μ _i	Relative loss factor of material at H \rightarrow 0	
U	RMS value of voltage	V
Û	Peak value of voltage	V
V _e	Effective magnetic volume	mm ³
Z	Complex impedance	Ω
Z _n	Normalized impedance $ Z _n = Z /N^2 \times \varepsilon (I_e/A_e)$	Ω /mm

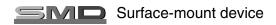
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Symbols and terms

Symbol	Meaning	Unit
α	Temperature coefficient (TK)	1/K
α_{F}	Relative temperature coefficient of material	1/K
α_{e}	Temperature coefficient of effective permeability	1/K
r	Relative permittivity	
Þ	Magnetic flux	Vs
1	Efficiency of a transformer	
В	Hysteresis material constant	mT-1
li	Hysteresis core constant	$A^{-1}H^{-1/2}$
'S	Magnetostriction at saturation magnetization	
,	Relative complex permeability	
0	Magnetic field constant	Vs/Am
a	Relative amplitude permeability	
app	Relative apparent permeability	
е	Relative effective permeability	
i	Relative initial permeability	
p	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)	
p	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)	
r	Relative permeability	
rev	Relative reversible permeability	
S S	Relative real (inductive) component of $\overline{\mu}$ (for series components)	
s S	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)	
tot	Relative total permeability	
	derived from the static magnetization curve	
	Resistivity	Ω m $^{-1}$
I/A	Magnetic form factor	mm ⁻¹
Cu	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	s
)	Angular frequency; $\omega = 2 \Pi f$	s ⁻¹

All dimensions are given in mm.





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